SN74AUC1G80 SINGLE POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP

SCES388H - MARCH 2002 - REVISED FEBRUARY 2004

- **Available in the Texas Instruments** NanoStar[™] and NanoFree[™] Packages
- Optimized for 1.8-V Operation and Is 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- Ioff Supports Partial-Power-Down Mode Operation
- Sub 1-V Operable
- Max t_{pd} of 1.9 ns at 1.8 V
- Low Power Consumption, 10-µA Max ICC
- ±8-mA Output Drive at 1.8 V
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DBV OR DCK PACKAGE (TOP VIEW) D $\square \vee_{\mathsf{CC}}$ CLK [GND 3 YEA OR YZA PACKAGE (BOTTOM VIEW) 03 40 Q CLK 02

0150

D

description/ordering information

This single positive-edge-triggered D-type flip-flop is operational at 0.8-V to 2.7-V V_{CC}, but is designed specifically for 1.65-V to 1.95-V V_{CC} operation.

When data at the data (D) input meets the setup time requirement, the data is transferred to the \overline{Q} output on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using Ioff. The Ioff circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

TA	PACKAGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING‡	
	NanoStar™ WCSP (DSBGA) – YEA	Tape and reel	SN74AUC1G80YEAR	1117
-40°C to 85°C	NanoFree™ WCSP (DSBGA) – YZA (Pb-free)	Tape and reel	SN74AUC1G80YZAR	UX_
	SOT (SOT-23) – DBV	Tape and reel	SN74AUC1G80DBVR	U80_
	SOT (SC-70) - DCK	Tape and reel	SN74AUC1G80DCKR	UX_

[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site. YEA/YZA: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoStar and NanoFree are trademarks of Texas Instruments.

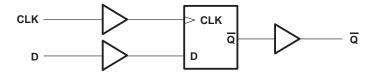


SCES388H - MARCH 2002 - REVISED FEBRUARY 2004

FUNCTION TABLE

INPU	JTS	OUTPUT
CLK	D	Q
1	Н	L
\uparrow	L	Н
L	Χ	\overline{Q}_0

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Voltage range applied to any output in the high-impedance or power-off state, $V_{\mbox{\scriptsize O}}$	
(see Note 1)	–0.5 V to 3.6 V
Output voltage range, V _O (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I _{OK} (V _O < 0)	
Continuous output current, I _O	±20 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 2): DBV package	206°C/W
DCK package	
YEA/YZA package	
Storage temperature range, T _{stq}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
VCC	Supply voltage		0.8	2.7	V
		V _{CC} = 0.8 V	VCC		
V_{IH}	High-level input voltage	$V_{CC} = 1.1 \text{ V to } 1.95 \text{ V}$	0.65×V _{CC}		V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		
		V _{CC} = 0.8 V		0	
V_{IL}	Low-level input voltage	$V_{CC} = 1.1 \text{ V to } 1.95 \text{ V}$		0.35 × V _{CC}	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	
VI	Input voltage		0	3.6	V
VO	Output voltage		0	Vcc	V
		V _{CC} = 0.8 V		V _{CC} -0.7 -3	
		V _{CC} = 1.1 V		-3	
lOH	High-level output current	V _{CC} = 1.4 V		-5	mA
		V _{CC} = 1.65 V		-8	
		V _{CC} = 2.3 V		-9	
		V _{CC} = 0.8 V		0.7	
		V _{CC} = 1.1 V		3	
loL	Low-level output current	V _{CC} = 1.4 V		5	mA
		V _{CC} = 1.65 V		8	
		V _{CC} = 2.3 V		9	
Δt/Δν	Input transition rise or fall rate	•		20	ns/V
TA	Operating free-air temperature		-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

P/	ARAMETER	TEST CON	DITIONS	v _{CC}	MIN	TYP [†]	MAX	UNIT			
		I _{OH} = -100 μA		0.8 V to 2.7 V	V _{CC} -0.1						
		$I_{OH} = -0.7 \text{ mA}$		0.8 V		0.55					
.,		$I_{OH} = -3 \text{ mA}$		1.1 V	0.8			.,			
VOH		$I_{OH} = -5 \text{ mA}$		1.4 V	1			V			
		I _{OH} = -8 mA		1.65 V	1.2						
		$I_{OH} = -9 \text{ mA}$		2.3 V	1.8						
		I _{OL} = 100 μA		0.8 V to 2.7 V		0.2					
		$I_{OL} = 0.7 \text{ mA}$		0.8 V		0.25					
.,		I _{OL} = 3 mA		1.1 V			0.3	V			
VOL		I _{OL} = 5 mA		1.4 V			0.4	V			
		I _{OL} = 8 mA		1.65 V			0.45				
		I _{OL} = 9 mA		2.3 V			0.6				
Ц	D or CLK input	$V_I = V_{CC}$ or GND		0 to 2.7 V			±5	μΑ			
l _{off}		V_I or $V_O = 2.7 V$		0			±10	μΑ			
ICC		$V_I = V_{CC}$ or GND,	IO = 0	0.8 V to 2.7 V			10	μΑ			
Ci		$V_I = V_{CC}$ or GND		2.5 V		2.5		pF			

[†] All typical values are at $T_A = 25^{\circ}C$.



SN74AUC1G80 SINGLE POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP

SCES388H - MARCH 2002 - REVISED FEBRUARY 2004

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		V _{CC} = 0.8 V	V _{CC} = ± 0.	= 1.2 V .1 V	V _{CC} = ± 0.	: 1.5 V 1 V	V _{CC} =		V _{CC} = ± 0.		UNIT
		TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency	50		200		225		250		275	MHz
t _W	Pulse duration, CLK high or low	4.6	1.7		1.7		1.7		1.7		ns
t _{su}	Setup time before CLK↑, Data high or low	1.6	1.1		0.8		0.6		0.5		ns
th	Hold time, data after CLK↑	0	0		0.1		0.1		0.1	·	ns

switching characteristics over recommended operating free-air temperature range, $C_L = 15 pF$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 0.8 V	V _{CC} = ± 0.	1.2 V 1 V	V _{CC} =		•	C = 1.8 0.15 V		V _{CC} = ± 0.		UNIT
	(INPOT)	(001F01)	TYP	MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX	
f _{max}			50	200		225		250			275		MHz
t _{pd}	CLK	IQ	5	1	3.9	0.8	2.5	0.3	1	1.9	0.3	1.3	ns

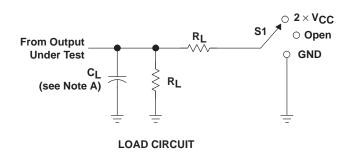
switching characteristics over recommended operating free-air temperature range, C_L = 30 pF (unless otherwise noted) (see Figure 1)

PARAMETER	PARAMETER FROM TO		V _{CC} = 1.8 V ± 0.15 V			V _{CC} = 2.5 V ± 0.2 V		UNIT
	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	
f _{max}			250			275		ns
^t pd	CLK	Q	0.8	1.5	2.4	0.6	1.8	ns

operating characteristics, T_A = 25°C

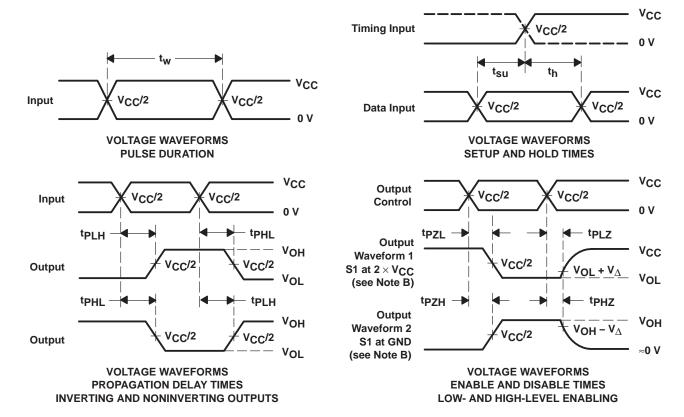
	PARAMETER	TEST CONDITIONS	V _{CC} = 0.8 V	V _{CC} = 1.2 V TYP	V _{CC} = 1.5 V TYP	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	UNIT
C _{pd}	Power dissipation capacitance	f = 10 MHz	18	18	18	18.5	20.5	pF

PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	2×V _{CC}
tPHZ/tPZH	GND

VCC	CL	RL	$v_{\scriptscriptstyle\Delta}$
0.8 V	15 pF	2 k Ω	0.1 V
1.2 V \pm 0.1 V	15 pF	2 k Ω	0.1 V
1.5 V \pm 0.1 V	15 pF	2 k Ω	0.1 V
1.8 V \pm 0.15 V	15 pF	2 k Ω	0.15 V
2.5 V \pm 0.2 V	15 pF	2 k Ω	0.15 V
1.8 V \pm 0.15 V	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	30 pF	500 Ω	0.15 V



NOTES: A. C_L includes probe and jig capacitance.

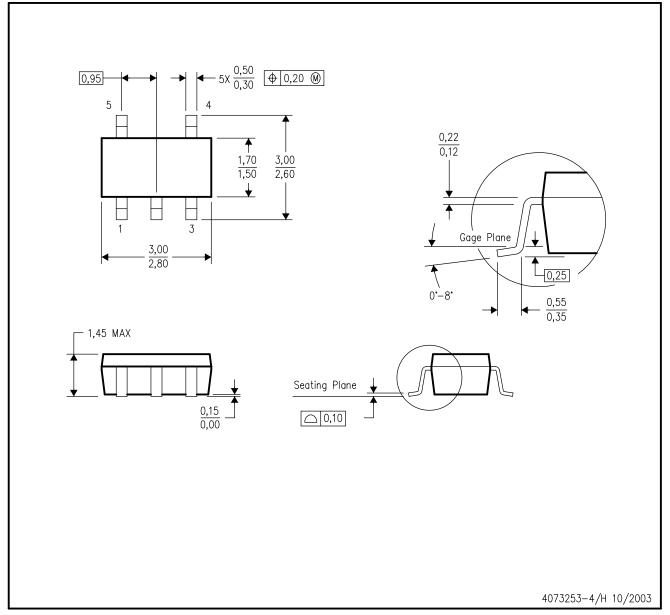
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , slew rate \geq 1 V/ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



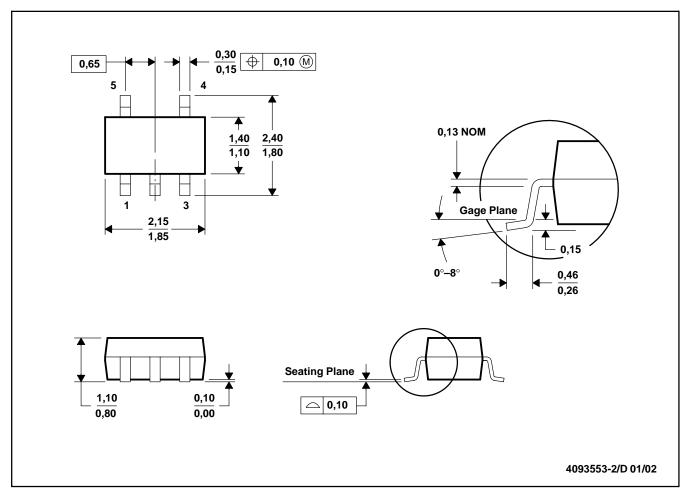
NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- C. Body dimensions do not include mold fla D. Falls within JEDEC MO—178 Variation AA. Body dimensions do not include mold flash or protrusion.



DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

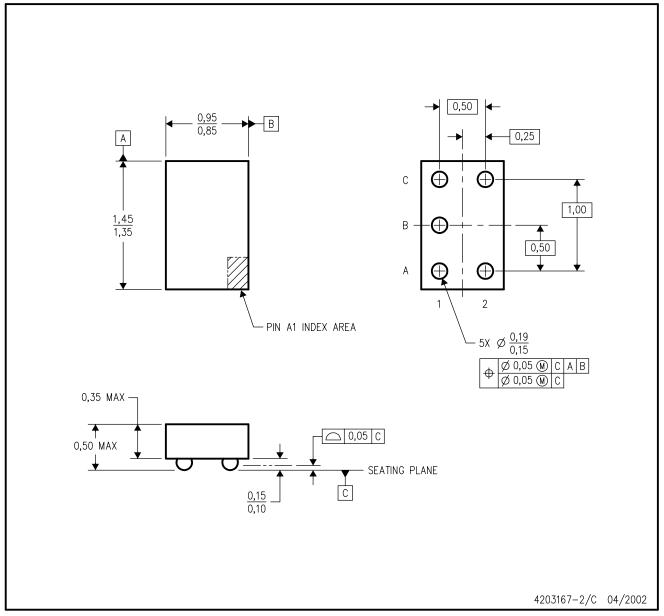
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion.

D. Falls within JEDEC MO-203

YEA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

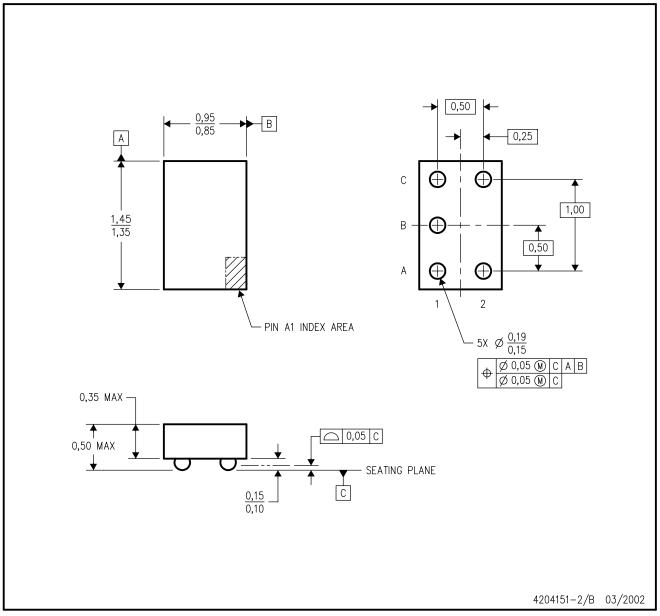
- B. This drawing is subject to change without notice.
- C. NanoStar \mathbf{M} package configuration.
- D. Package complies to JEDEC MO-211 variation EA.
- E. This package is tin-lead (SnPb). Refer to the 5 YZA package (drawing 4204151) for lead-free.

NanoStar is a trademark of Texas Instruments.



YZA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

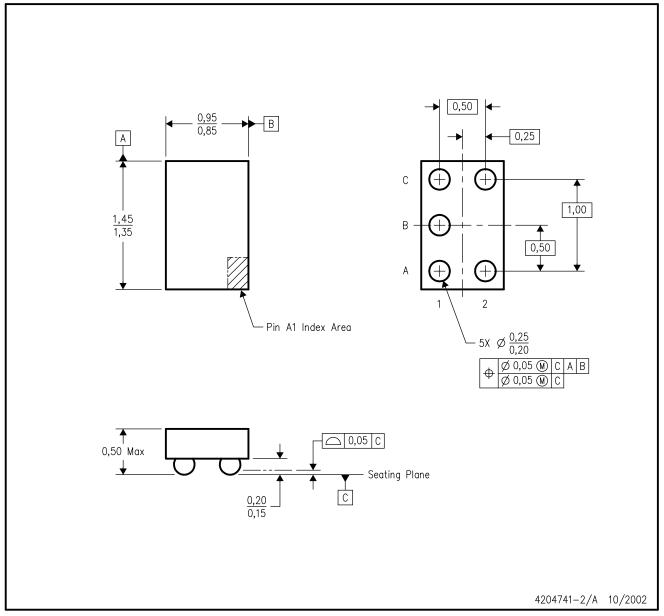
- B. This drawing is subject to change without notice.
- C. NanoFree $^{\text{TM}}$ package configuration.
- D. Package complies to JEDEC MO-211 variation EA.
- E. This package is lead-free. Refer to the 5 YEA package (drawing 4203167) for tin-lead (SnPb).

NanoFree is a trademark of Texas Instruments.



YZP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

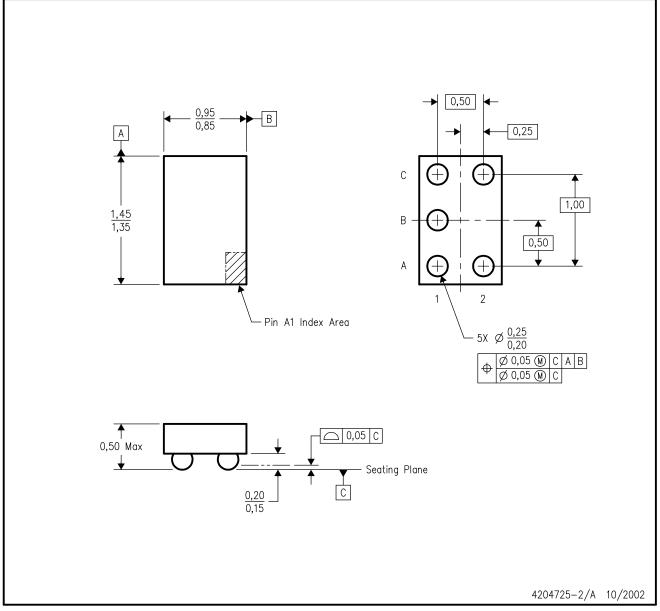
- B. This drawing is subject to change without notice.
- C. NanoFree $^{\text{TM}}$ package configuration.
- D. This package is lead-free. Refer to the 5 YEP package (drawing 4204725) for tin-lead (SnPb).

NanoFree is a trademark of Texas Instruments.



YEP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. NanoStar \mathbf{M} package configuration.
- D. This package is tin-lead (SnPb). Refer to the 5 YZP package (drawing 4204741) for lead-free.

NanoStar is a trademark of Texas Instruments.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless
Data Converters DSP Interface Logic Power Mgmt	dataconverter.ti.com dsp.ti.com interface.ti.com logic.ti.com power.ti.com	Broadband Digital Control Military Optical Networking Security Telephony Video & Imaging	www.ti.com/broadband www.ti.com/digitalcontrol www.ti.com/military www.ti.com/opticalnetwor www.ti.com/security www.ti.com/telephony www.ti.com/video

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2004, Texas Instruments Incorporated